

XP-002183611

AN - 1983-836782 [49]  
A - [001] 013 03- 075 140 273 308 328 357 456 46& 463 477 506 509 623 627  
628 723  
AP - JP19820070729 19820427  
CPY - KOBE  
DC - A32 A85 L03 P73  
FS - CPI;GMPI  
IC - B32B5/22 ; B32B27/42 ; C08J5/24 ; H01B17/60 ; H05K1/03  
KS - 0011 0034 0037 0216 0229 1277 2317 2467 2491 2544 2551 2718 2740  
MC - A05-C01 A11-B09 A12-E07A A12-S08A L03-H04E1  
PA - (KOBE ) SHIN KOBE ELECTRIC MACHINERY  
PN - JP58187434 A 19831101 DW198349 004pp  
- JP62021813B B 19870514 DW198723 000pp  
PR - JP19820070729 19820427  
XA - C1983-119522  
XIC - B32B-005/22 ; B32B-027/42 ; C08J-005/24 ; H01B-017/60 ; H05K-001/03  
XP - N1983-218832  
AB - J58187434 Mfr. comprises laminating and moulding prepregs. which are  
produced by impregnating (a) phenol resin varnish into base material  
by two stages, undercoating and top coating. Varnish (a) for the top  
coating contains 0.5-5 pts. wt. of (b) aminocarboxylic acid salt cpd.  
based on 100 pts. wt. of solid resin. Pref. cpd. (b) is that being  
soluble or homogeneously dispersible in (a). It is e.g. EDTA,  
diethylene triamine hexaacetic acid, diethanol glycine, etc.  
- The laminated sheet is used as an insulated base plate of a printed  
circuit plate. The laminated sheet prevents migration of silver in a  
conductive coating for an electric circuit, since (b) reacts with  
silver ion to form a water-insol. chelate.  
- When the content of (b) is above 5 pts. wt., the laminated sheet  
lowers in thermoresistance on soldering, chemical resistance, etc.(0/2)  
IW - MANUFACTURE LAMINATE SHEET PCB BASE MOULD PREPREG BASED POLYPHENOL  
RESIN VARNISH  
IKW - MANUFACTURE LAMINATE SHEET PCB BASE MOULD PREPREG BASED POLYPHENOL  
RESIN VARNISH  
NC - 001  
OPD - 1982-04-27  
ORD - 1983-11-01  
PAW - (KOBE ) SHIN KOBE ELECTRIC MACHINERY  
TI - Mfg. laminate sheet used as PCB base - by moulding prepregs based on  
phenol] resin varnish